


Features

- Low Forward Voltage Drop
- Low Leakage Current
- Superior Reverse Avalanche Capability
- Excellent High Temperature Stability
- Patented Interlocking Clip Design for High Surge Current Capacity
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- ±16KV ESD Protection (HBM, 3B)
- ±25KV ESD Protection (IEC61000-4-2 Level 4, Air Discharge)
- **Lead Free Finish, RoHS Compliant (Note 1)**
- **“Green” Molding Compound (No Br, Sb)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: PowerDI[®]123
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Polarity Indicator: Cathode Band
- Terminals: Finish - Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.018 grams (approximate)



Top View

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _{RM}		
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Rectified Output Current (See Figure 1)	I _O	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	75	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance	R _{θJS}	5	°C/W
Thermal Resistance Junction to Soldering (Note 2)	R _{θJA}	175	
Thermal Resistance Junction to Ambient (Note 3)	R _{θJA}	100	
Thermal Resistance Junction to Ambient (Note 4)			
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

- Notes:
1. RoHS revision 13.2.2003. High temperature solder exemption applied, see *EU Directive Annex Note 7*.
 2. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
 3. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
 4. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	30	-	-	V	$I_R = 250\mu\text{A}$
Forward Voltage Drop	V_F	-	0.23	0.28	V	$I_F = 0.1\text{A}, T_J = 25^\circ\text{C}$
		-	0.34	0.39		$I_F = 1.0\text{A}, T_J = 25^\circ\text{C}$
		-	0.40	0.45		$I_F = 2.0\text{A}, T_J = 25^\circ\text{C}$
		-	0.50	-		$I_F = 4.0\text{A}, T_J = 125^\circ\text{C}$
		-	0.13	0.19		$I_F = 0.1\text{A}, T_J = 125^\circ\text{C}$
		-	0.275	0.33		$I_F = 1.0\text{A}, T_J = 125^\circ\text{C}$
Leakage Current (Note 5)	I_R	-	50	100	μA	$V_R = 5\text{V}, T_J = 25^\circ\text{C}$
		-	55	200	μA	$V_R = 30\text{V}, T_J = 25^\circ\text{C}$
		-	5	10	mA	$V_R = 5\text{V}, T_J = 125^\circ\text{C}$
		-	7	15	mA	$V_R = 30\text{V}, T_J = 125^\circ\text{C}$

Notes: 5. Short duration pulse test used to minimize self-heating effect.

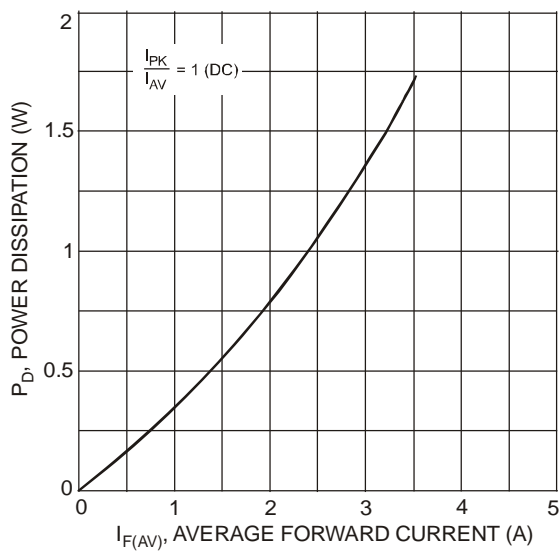


Fig. 1 Forward Power Dissipation

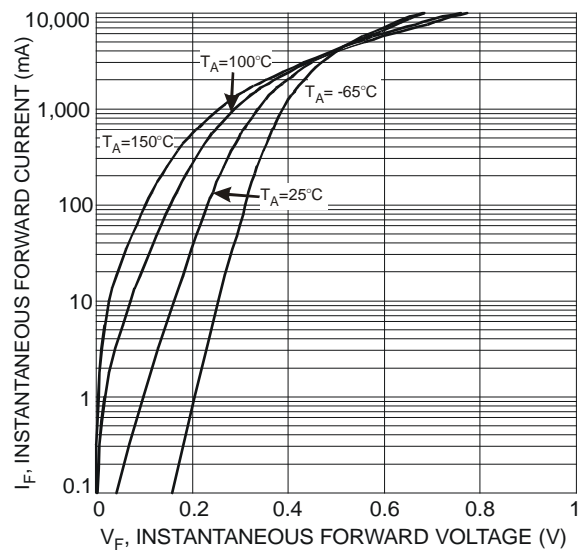


Fig. 2 Typical Forward Characteristics

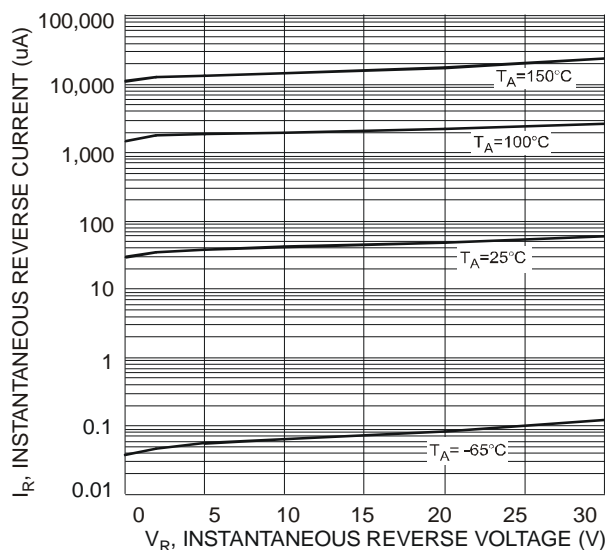


Fig. 3 Typical Reverse Characteristics

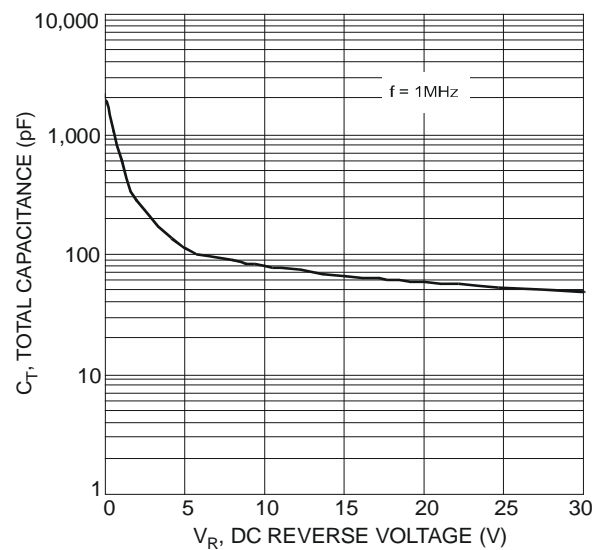


Fig. 4 Total Capacitance vs. Reverse Voltage

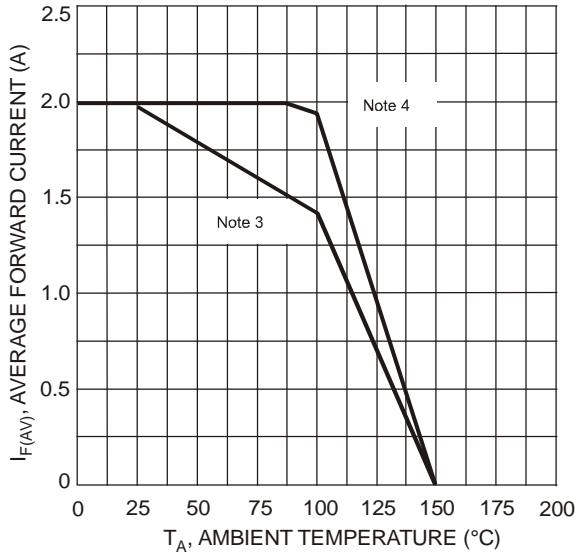


Fig. 5 Forward Current Derating Curve

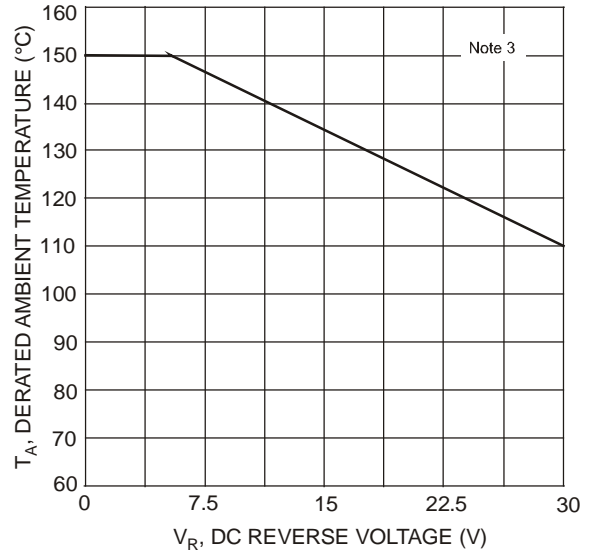


Fig. 6 Operating Temperature Derating

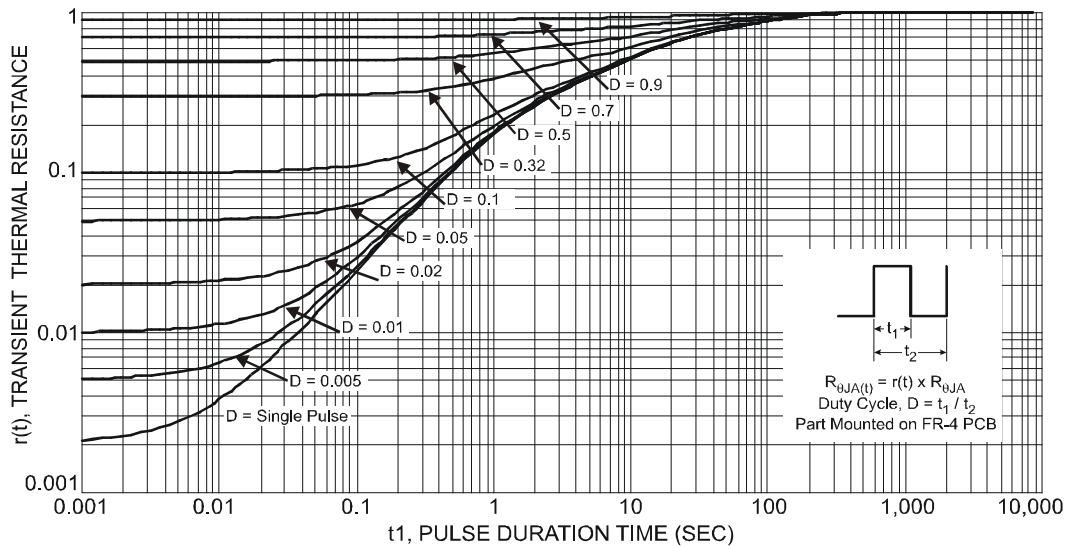


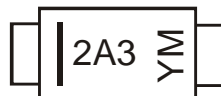
Fig. 7 Transient Thermal Resistance

Ordering Information (Note 6)

Part Number	Case	Packaging
SBR2A30P1-7	PowerDI [®] 123	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



2A3 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: T = 2006)
 M = Month (ex: 9 = September)

Date Code Key

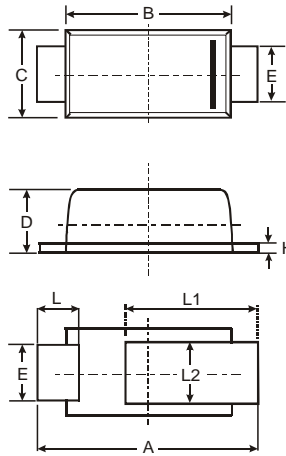
Year	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	T	U	V	W	X	Y	Z	A	B	C

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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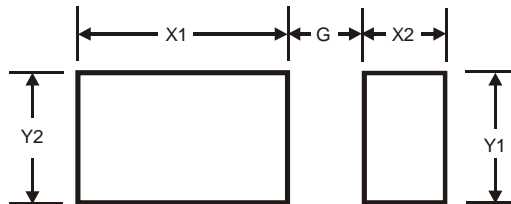
SBR2A30P1

Package Outline Dimensions



PowerDI [®] 123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.55	0.75	0.65
L1	1.80	2.20	2.00
L2	0.95	1.25	1.10
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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